Gurmeet Singh

(650) 793-1051   grmsingh@yahoo.com   1055 Manet Dr. #80, Sunnyvale CA 94087
https://swiftgurmeet.github.io/resume/

Summary

I have over 25 years of leading edge technical experience both as a leader and an individual contributor with a record of highly effective, flawless and prolific execution. My strengths include a vast array of skills and expertise, good communication/analytical skills and ingenuity.

Unable to relocate or travel overnight. U.S. citizen.

Experience

[18-PRESENT] CONSULTANT, CONFIDENTIAL

• Physical design methodology for a 7nm Machine Learning SoC. Design of global clock distribution network, spice modeling/simulation and ICC2 implementation. Setup custom compiler schematic and netlisting environment. Characterize PVT sensitivity of level shifters with spice simulations. Set up Redhawk seascape flow for EM/IR. Own a million gate low voltage design for place and route.

[16-17] CONSULTANT, ZGLUE INC.

• Physical design methodology and netlist-to-gds flow development in tcl using Cadence toolset. Also Assura physical verification and logical equivalence (lec) flows.
• Hierarchical implementation of an instance array design including floorplanning, power grid, pin placement, place and route, logical equivalence and physical verification.
• Abstract generation of analog macros and hierarchical instance to allow for through the block routing.
• Mixed-signal custom CAD support including SKILL programming
• Setup Virtuoso QRC extraction flow for full chip STA, set up and run full chip STA with Tempus, set up and run full chip LEC with Conformal. Silicon success.

[15-16] MACHINE LEARNING/SOFTWARE ENGINEER

• Data Science/Machine Learning/Programming
• Swift iOS Programming

[13-14] QUALCOMM TECHNOLOGIES, SENIOR STAFF ENGINEER

Design of the top level floorplan including power grid with multiple power domains, using CPF/UPF for a mixed signal design, automated floorplan generation with Tcl. Wrote power intent CPF from scratch. Full chip formal (LEC) and low power (CLP) verification using

Cadence tools. Apache Redhawk EM/IR debug and fixes. My leadership enabled a rare ahead of schedule tapeout. Received two Qualstars. Silicon success (WCD9335).

[12-13] CADENCE DESIGN SYSTEMS, STAFF APPLICATION ENGINEER

• Developed a complete, automated rtl2gds reference flow (14nm/finFET) using Cadence tools for a leading edge foundry to provide to its customers. Proven using the same flow, an implementation of an ARM A9 processor core including neon coprocessor@2.4GHz/Typ.

• Implemented a 28nm DDR-PHY IP for tapeout.

[11-12] SANDFORCE INC., PRINCIPAL ENGINEER

• Developed a 40 nm automated and optimized, tapeout ready, Cadence based implementation flow.
• Wrote Tcl scripts for a correct by construction, tunable flow used for all blocks.
• Developed automated, tapeout ready, STA setup using Primetime-SI using Tcl/Perl scripts.
• Implemented several large blocks at tapeout quality using the above flow ; the resulting GDSII were timing, LEC, LVS/DRC clean. Silicon success.
• Helped grow the size and capability of the physical design team and lead technical direction.

[08-11] CONTRACTOR/ENGINEER @(MULTIPLE)

• Setup 40nm Cadence based, automated, tapeout ready, block level implementation flow.
• Hierarchical physical implementation flow in 65nm technology using Cadence.
• Telecom ASIC: Implementation of two large blocks using Magma. Silicon Success.
• 65nm WiFi ASIC: Implementation of large block using Magma. Silicon Success.
• 65nm WiFi ASIC: Full chip EM/IR signoff using Apache-Redhawk. Silicon Success.

[06-08] TERANETICS, PRINCIPAL ENGINEER

130nm/65nm 10GBASE-T PHY ASIC: Implement many large blocks, some using x-route. Automate implementation, static timing analysis, logical equivalence and physical verification flows. Power estimation; power reduction using special cells. Silicon Success.

[04-06] AIRGO NETWORKS, PHYSICAL DESIGN MANAGER

Multiple WiFi ASICs: Implement many blocks using Magma. Automate PTSI STA, formal, Calibre PV flows. Full chip EM/IR signoff using Apache-Redhawk. Tapeout signoff/jobview. ECOs, I/O Spice sims, IP integration, Methodology, Project Management. Silicon success.

[01-04] TRANSMETA, SENIOR MEMBER, TECHNICAL STAFF

1.2/1.8GHz Efficeon CPUs: Implement Hypertransport unit with place and route tools; Register File design. ECOs. Setup latch compatible STA flow. Array and noise methodologies. Silicon Success.

[99-01] SUN MICROSYSTEMS, MEMBER, TECHNICAL STAFF

- UltraSparc V CPU: Custom circuit design of a content addressable register file and an arrayed random logic block
- 1.2GHz UltraSparc III CPU: Ported a dozen 130nm dynamic circuit blocks, including adders up to 64-bits, from 180nm to 130nm. Wrote a Pathmill API hook in C to automate generation of timing models. Silicon success.

[97-99] INTEL CORPORATION, DESIGN ENGINEER

- 833MHz Pentium III Xeon CPU: High speed dynamic circuit design for L2Cache ECC encoder, L2 Cache STA analysis and EM/IR verification. Silicon success.
- 600 MHz Pentium III CPU : GTL I/O circuit design including one invention disclosure. Silicon success.

[94-97] ST MICROELECTRONICS, DESIGN ENGINEER

Circuit Design of 32kx8, 128kx8 SRAMs. Silicon success. CAD setup. Reverse engineer a register file and re-implement, verify functionality using verilog switch level simulation. Silicon success.

Education

[1989-93] MS, ELECTRICAL COMMUNICATION, INDIAN INSTITUTE OF SCIENCE.

[1986-89] B.SC., PHYSICS, DELHI UNIVERSITY.